

Electroformed Bond Hub Blades

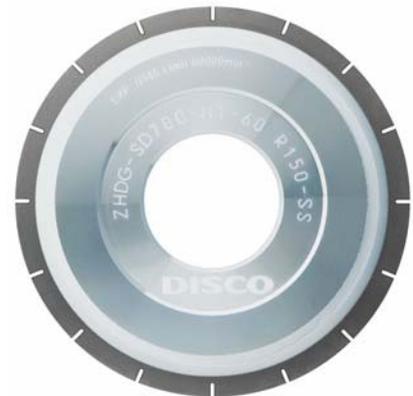
ZHDG SERIES

Electroformed hub blades producing high quality substrate dicing

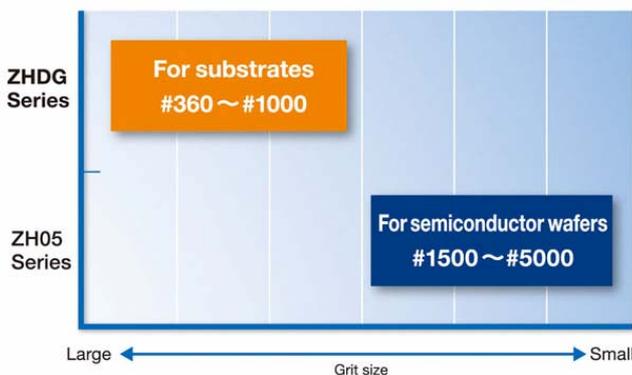
Easy-to-handle hub blade for dicing substrates An extensive lineup of grit sizes and concentrations for high quality processing

The ZHDG series developed for dicing various substrates adopts a larger grit size compared to the hub blades for semiconductor wafers. Also, the abundant concentration lineup meets a number of different customer requests.

- Improved operability thanks to the aluminum base as compared with standard hubless type blades for dicing substrates.
- Selectable from a lineup with an abundant variety of grit sizes and concentrations.
- Reduction in resin/metal burring by selecting a low concentration.



■ ZHDG series



Applications

Chip LED board, Various types of semiconductor packages, etc.

